

Table 1. Electrical Specifications Temp = 25°C, V_{DD} = 3.3V

| Parameter | Path | Condition | Min | Typ | Max | Unit |
|---|---------|---------------------------------------|-----|------|-----|------|
| Operational frequency | | | 0.1 | | 6 | GHz |
| Insertion loss | RFC–RFX | 0.1–2.4 GHz | | 0.80 | 1.0 | dB |
| | | 2.4–5.8 GHz | | 0.95 | 1.1 | dB |
| | | 5.8–6.0 GHz | | 0.95 | 1.1 | dB |
| Isolation | RFX–RFX | 0.1–2.4 GHz | 49 | 51 | | dB |
| | | 2.4–5.8 GHz | 39 | 41 | | dB |
| | | 5.8–6.0 GHz | 39 | 41 | | dB |
| Isolation | RFC–RFX | 0.1–2.4 GHz | 44 | 47 | | dB |
| | | 2.4–5.8 GHz | 39 | 41 | | dB |
| | | 5.8–6.0 GHz | 40 | 43 | | dB |
| Return loss (common and active port) | RFX | 0.1–2.4 GHz | | 19 | | dB |
| | | 2.4–5.8 GHz | | 16 | | dB |
| | | 5.8–6.0 GHz | | 16 | | dB |
| Return loss (terminated port) | RFX | 0.1–2.4 GHz | | 23 | | dB |
| | | 2.4–5.8 GHz | | 23 | | dB |
| | | 5.8–6.0 GHz | | 24 | | dB |
| Input 0.1 dB compression point ¹ | RFC–RFX | 0.6–4.0 GHz | | 39.5 | | dBm |
| Input IP3 ² | RFC–RFX | 0.8–2.7 GHz | | 65 | | dBm |
| Input IP2 ² | RFC–RFX | 0.8–2.7 GHz | | 120 | | dBm |
| Switching time | | 50% CTRL to 90% or 10% of final value | | 500 | 700 | ns |

Notes: 1. The input 0.1dB compression point is a linearity figure of merit. Refer to *Table 3* for the operating RF input power (50mW).
2. The input intercept point remains invariant over the full supply range as defined in *Table 3*

Figure 3. Pin Configuration (Top View)

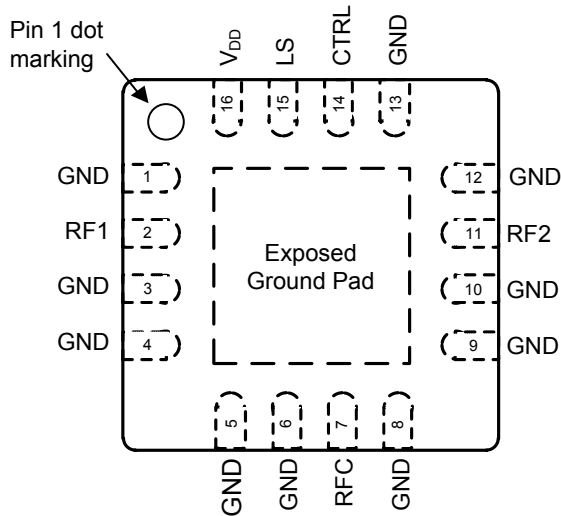


Table 2. Pin Descriptions

| Pin # | Pin Name | Description |
|---------------------------------|------------------|--|
| 1, 3, 4, 5, 6, 8, 9, 10, 12, 13 | GND | Ground |
| 2 | RF1 ¹ | RF port 1 |
| 7 | RFC ¹ | RF common |
| 11 | RF2 ¹ | RF port 2 |
| 14 | CTRL | Digital control logic input |
| 15 | LS | Logic Select - used to determine the definition for the CTRL pin (see Table 5) |
| 16 | V _{DD} | Supply voltage (nominal 3.3V) |
| Pad | GND | Exposed pad: ground for proper operation |

Note 1: RF pins 2, 7 and 11 must be at 0V DC. The RF pins do not require DC blocking capacitors for proper operation if the 0V DC requirement is met

Table 3. Operating Ranges

| Parameter | Symbol | Min | Typ | Max | Unit |
|--|-------------------------|------|-----|------------------------|-------------------|
| Supply voltage | V _{DD} | 2.3 | | 5.5 | V |
| Supply current | I _{DD} | | 120 | 200 | μA |
| Digital input high (CTRL) | V _{IH} | 1.17 | | 3.6 | V |
| Digital input low (CTRL) | V _{IL} | -0.3 | | 0.6 | V |
| RF input power, CW 0.1–0.6 GHz 0.6–4.0 GHz 4.0–6.0 GHz | P _{MAX,CW} | | | 27 Fig. 4 Fig. 4 | dBm dBm dBm |
| RF input power, pulsed ¹ 0.1–0.6 GHz 0.6–4.0 GHz 4.0–6.0 GHz | P _{MAX,PULSED} | | | 27 Fig. 4 Fig. 4 | dBm dBm dBm |
| RF input power into terminated ports, CW | P _{MAX,TERM} | | | 22 | dBm |
| Operating temperature range | T _{OP} | -40 | +25 | +125 | °C |

Note 1: Pulsed, 5% duty cycle of 4620 μs period, 50μs

Table 4. Absolute Maximum Ratings

| Parameter/Condition | Symbol | Min | Max | Unit |
|--|----------------------|------|------------------|-------------------|
| Supply voltage | V _{DD} | -0.3 | 5.5 | V |
| Digital input voltage (CTRL) | V _{CTRL} | -0.3 | 3.6 | V |
| LS input voltage | V _{LS} | -0.3 | 3.6 | V |
| Maximum input power 0.1–0.6 GHz 0.6–4.0 GHz 4.0–6.0 GHz | P _{MAX,ABS} | | 30 39 37.5 | dBm dBm dBm |
| Storage temperature range | T _{ST} | -65 | +150 | °C |
| ESD voltage HBM ¹ RF pins to GND All pins | V _{ESD,HBM} | | 3000 1500 | V V |
| ESD voltage MM ² , all pins | V _{ESD,MM} | | 200 | V |
| ESD voltage CDM ³ , all pins | V _{ESD,CDM} | | 1000 | V |

Notes: 1. Human Body Model (MIL-STD 883 Method 3015)
2. Machine Model (JEDEC JESD22-A115)
3. Charged Device Model (JEDEC JESD22-C101)

Exceeding absolute maximum ratings may cause permanent damage. Operation should be restricted to the limits in the Operating Ranges table. Operation between operating range maximum and absolute maximum for extended periods may reduce reliability.

Electrostatic Discharge (ESD) Precautions

When handling this UltraCMOS® device, observe the same precautions that you would use with other ESD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the rating specified.

Latch-Up Avoidance

Unlike conventional CMOS devices, UltraCMOS® devices are immune to latch-up.

Switching Frequency

The PE42423 has a maximum 25 kHz switching rate. Switching frequency describes the time duration between switching events. Switching time is the time duration between the point the control signal reaches 50% of the final value and the point the output signal reaches within 10% or 90% of its target value.

Table 5. Control Logic Truth Table

| LS | CTRL | RFC-RF1 | RFC-RF2 |
|----|------|---------|---------|
| 0 | 0 | off | on |
| 0 | 1 | on | off |
| 1 | 0 | on | off |
| 1 | 1 | off | on |

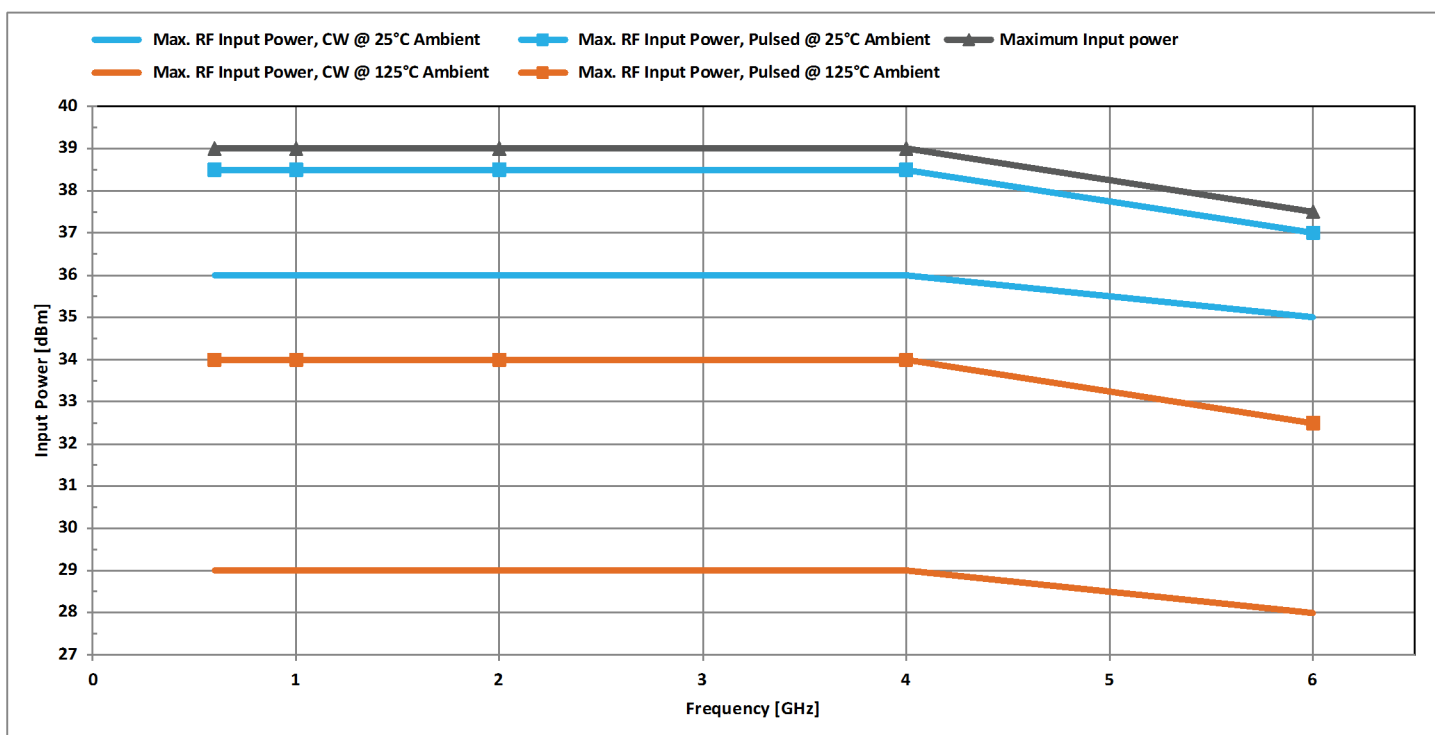
Moisture Sensitivity Level

The Moisture Sensitivity Level rating for the PE42423 in the 16-lead 3x3 mm QFN package is MSL3.

Logic Select (LS)

The Logic Select feature is used to determine the definition for the CTRL pin.

Figure 4. Power De-rating Curve for 600 MHz – 6 GHz



Typical Performance Data @ 25°C and $V_{DD} = 3.3V$ unless otherwise specified

Figure 5. Insertion Loss vs. Temp (RFC–RFX)

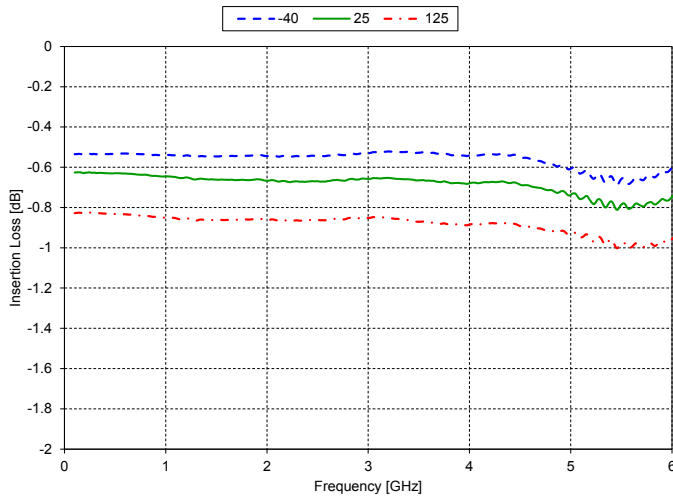


Figure 6. Insertion Loss vs. V_{DD} (RFC–RFX)

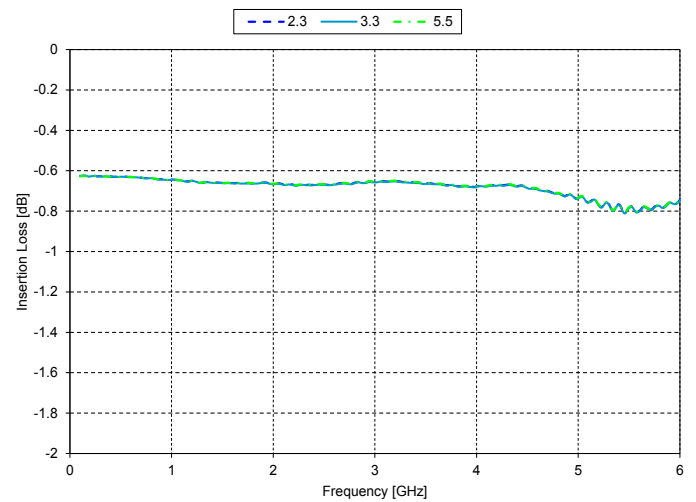


Figure 7. RFX Port Return Loss vs. Temp

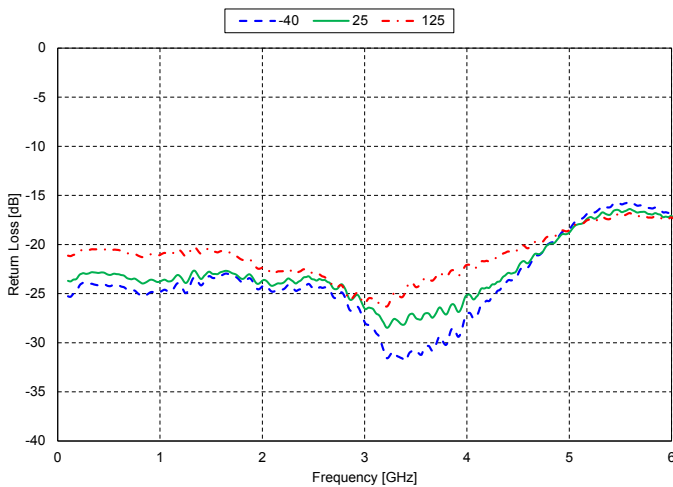
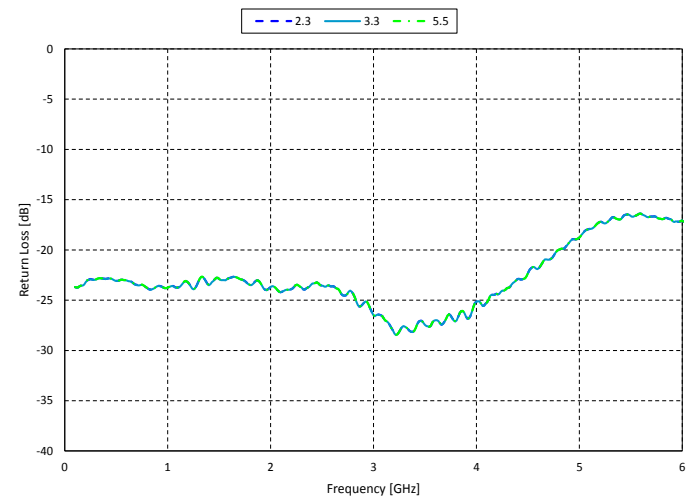


Figure 8. RFX Port Return Loss vs. V_{DD}



Typical Performance Data @ 25°C and $V_{DD} = 3.3V$ unless otherwise specified

Figure 9. Terminated Port Return Loss vs. Temp (RFX Active)

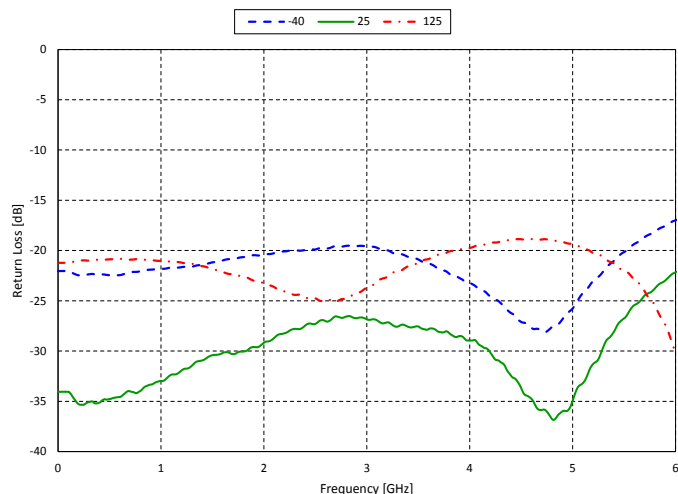


Figure 10. Terminated Port Return Loss vs. V_{DD} (RFX Active)

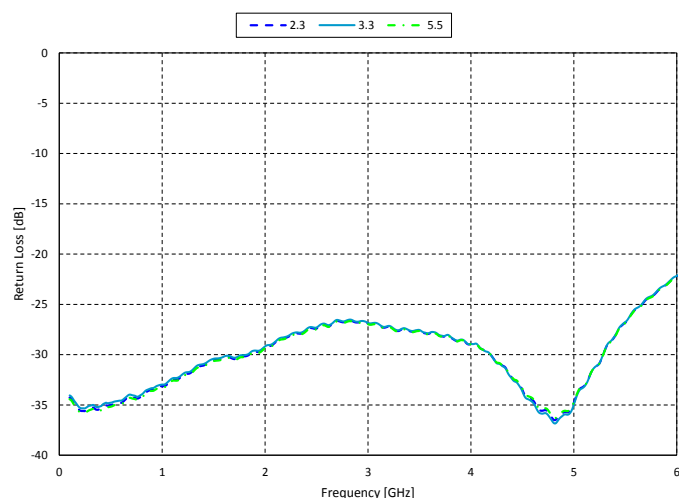


Figure 11. Isolation vs. Temp (RFX-RFX, RFX Active)

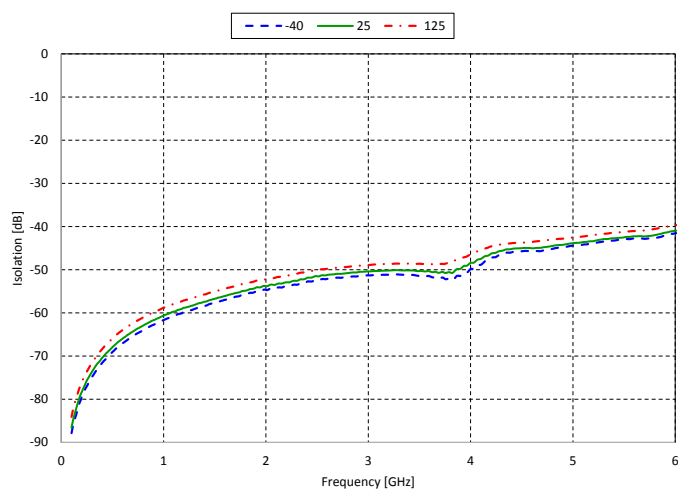
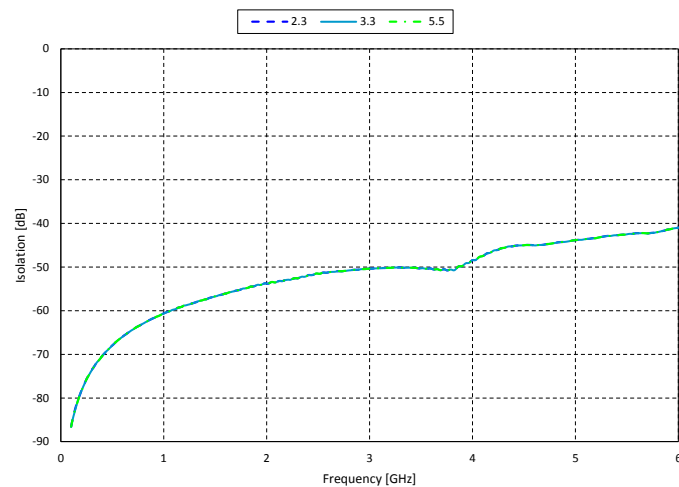


Figure 12. Isolation vs. V_{DD} (RFX-RFX, RFX Active)



Typical Performance Data @ 25°C and V_{DD} = 3.3V unless otherwise specified

Figure 13. Isolation vs. Temp
(RFC–RFX, RFX Active)

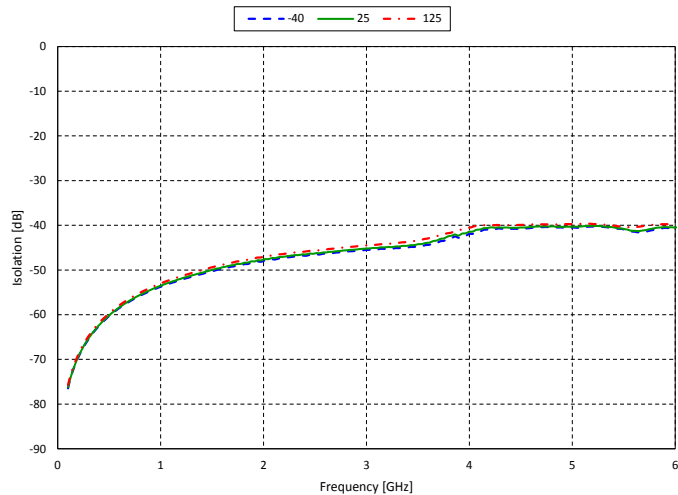
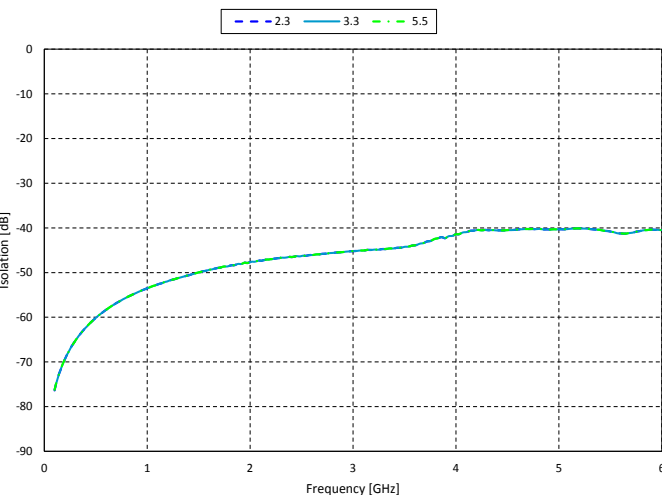


Figure 14. Isolation vs. V_{DD}
(RFC–RFX, RFX Active)

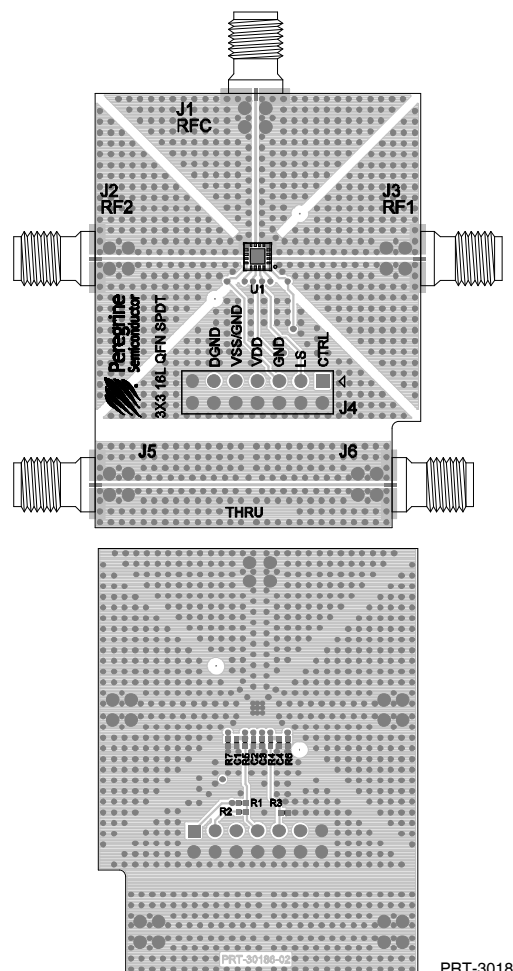


Evaluation Kit

The SPDT switch evaluation board was designed to ease customer evaluation of PSEMI's PE42423. The RF common port is connected through a 50 Ω transmission line via the SMA connector, J1. RF1 and RF2 ports are connected through 50 Ω transmission lines via SMA connectors J2 and J3, respectively. A 50 Ω through transmission line is available via SMA connectors J5 and J6, which can be used to de-embed the loss of the PCB. J4 provides DC and digital inputs to the device.

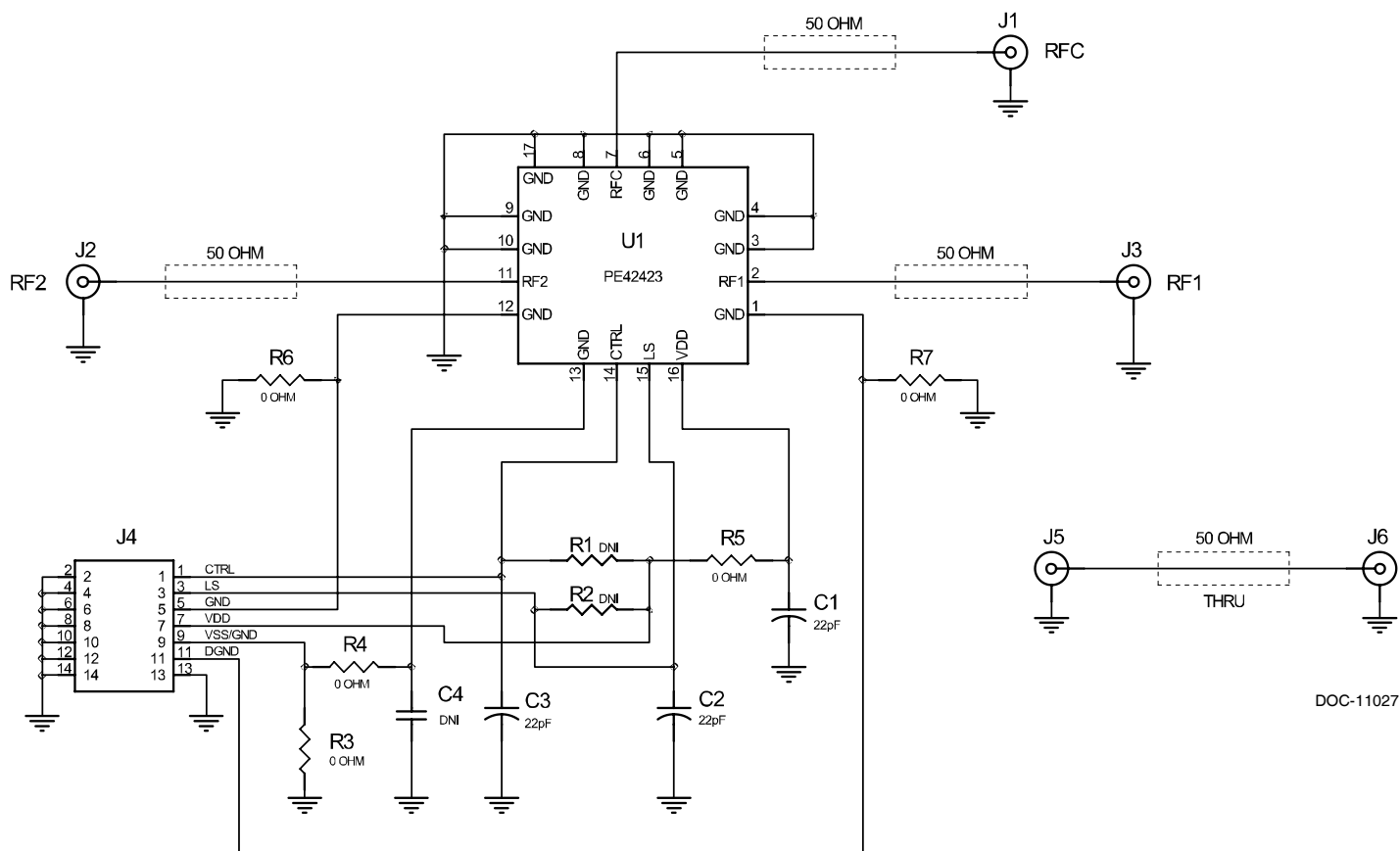
For the true performance of the PE42423 to be realized, the PCB should be designed in such a way that RF transmission lines and sensitive DC I/O traces are heavily isolated from one another.

Figure 15. Evaluation Kit Layout



PRT-30186

Figure 16. Evaluation Board Schematic



DOC-11027

- Notes:
1. Use PRT-30186-2 PCB
 2. CAUTION: Contains parts and assemblies susceptible to damage by electrostatic discharge (ESD)

Figure 17. Package Drawing
16-lead 3x3 mm QFN

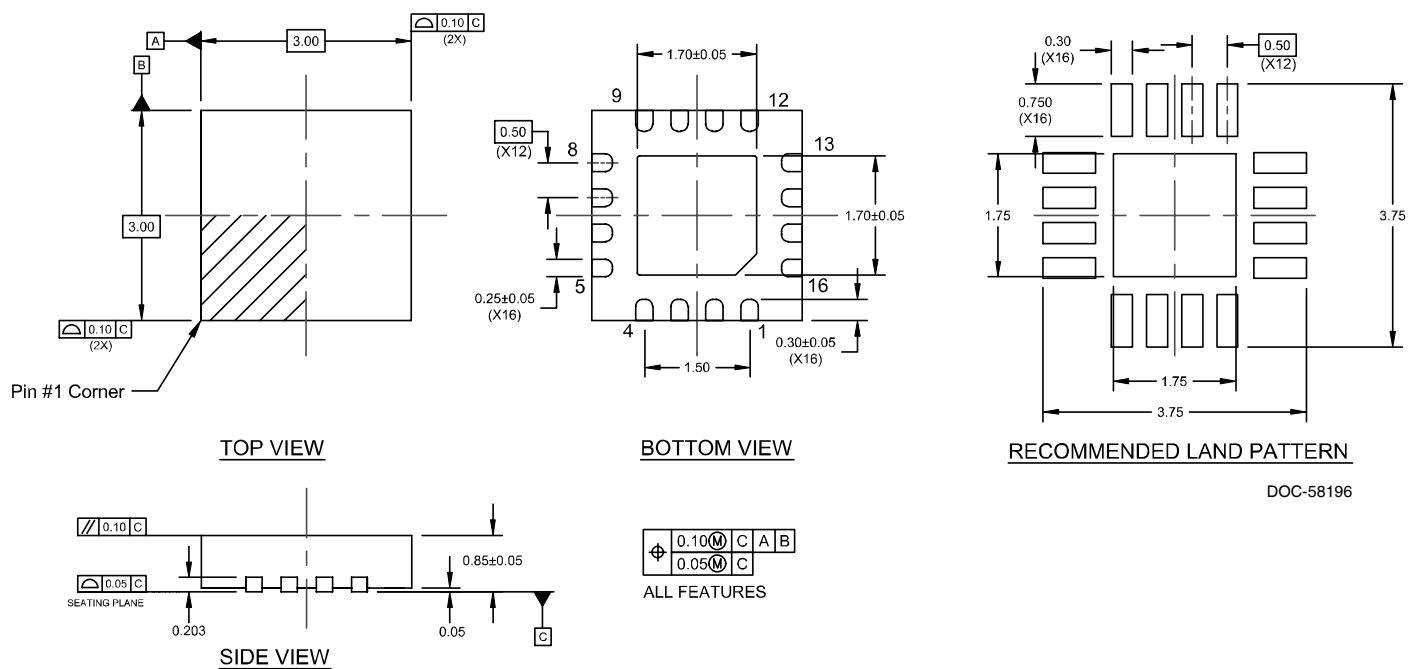
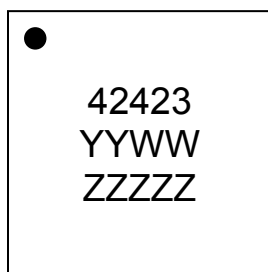


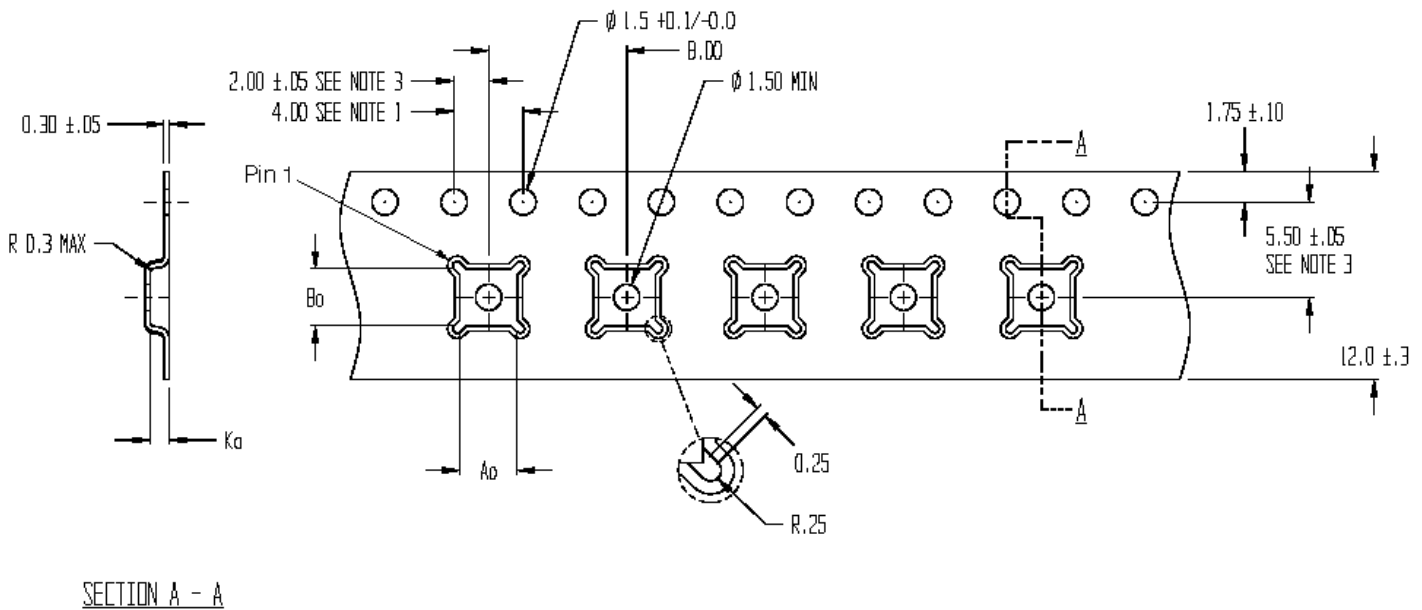
Figure 18. Top Marking Specifications



17-0009

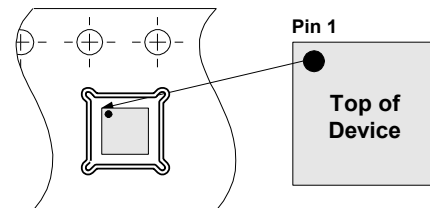
- = Pin 1 designator
- YYWW = Date code
- ZZZZZ = Last five digits of lot number

Figure 19. Tape and Reel Specifications



Notes: 1. 10 sprocket hole pitch cumulative tolerance ± 0.2
2. Camber in compliance with EIA 481
3. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole

$A_o = 3.30$
 $B_o = 3.30$
 $K_o = 1.10$



Device Orientation in Tape

Table 6. Ordering Information

| Order Code | Description | Package | Shipping Method |
|------------|------------------------|--------------------------|-----------------|
| PE42423B-Z | PE42423 SPDT RF switch | Green 16-lead 3x3 mm QFN | 3000 units/T&R |
| EK42423-03 | PE42423 Evaluation kit | Evaluation kit | 1/Box |

Sales Contact and Information

For sales and contact information please visit www.psemi.com.

Advance Information: The product is in a formative or design stage. The datasheet contains design target specifications for product development. Specifications and features may change in any manner without notice.
Preliminary Specification: The datasheet contains preliminary data. Additional data may be added at a later date. pSemi reserves the right to change specifications at any time without notice in order to supply the best possible product.
Product Specification: The datasheet contains final data. In the event pSemi decides to change the specifications, pSemi will notify customers of the intended changes by issuing a CNF (Customer Notification Form).
The information in this document is believed to be reliable. However, pSemi assumes no liability for the use of this information. Use shall be entirely at the user's own risk.

No patent rights or licenses to any circuits described in this document are implied or granted to any third party. pSemi's products are not designed or intended for use in devices or systems intended for surgical implant, or in other applications intended to support or sustain life, or in any application in which the failure of the pSemi product could create a situation in which personal injury or death might occur. pSemi assumes no liability for damages, including consequential or incidental damages, arising out of the use of its products in such applications.

The Peregrine Semiconductor name, Peregrine Semiconductor logo and UltraCMOS are registered trademarks and the pSemi name, pSemi logo, HaRP and DuNE are trademarks of pSemi Corporation in the U.S. and other countries.

pSemi products are protected under one or more of the following U.S. patents: patents.psemi.com.